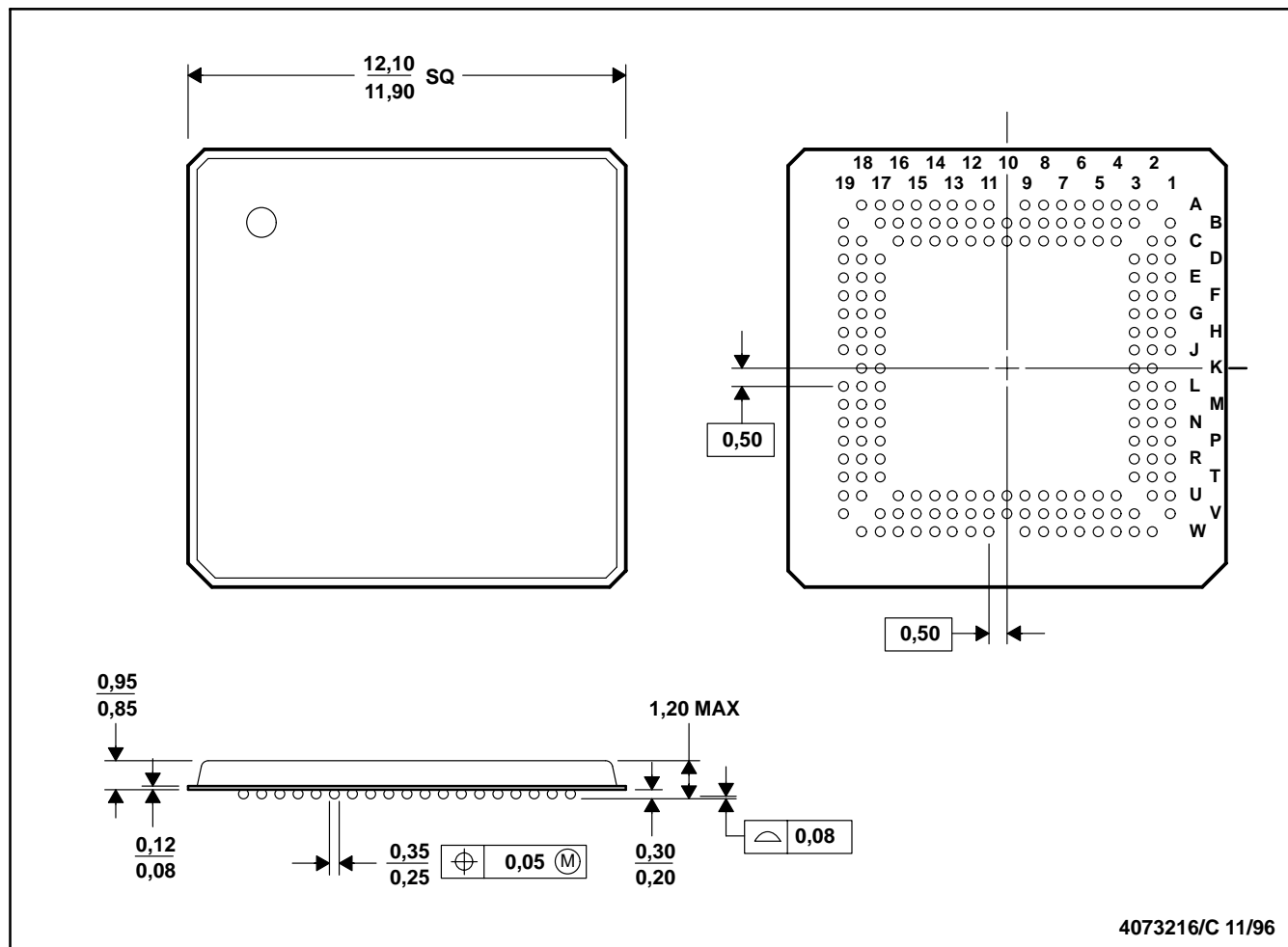


## GGG (S-PBGA-N176)

## PLASTIC BALL GRID ARRAY PACKAGE



- NOTES: A. All linear dimensions are in millimeters.  
B. This drawing is subject to change without notice.

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